

REMARKS

Claims 1 and 3 - 11 are in the application.

Of these claims, claims 10 and 11 are withdrawn from consideration.

With respect to the objection to claim 1, the Examiner will note that the preamble of the claim has been corrected.

Also, with respect to the objection to the specification, claim 2 has been deleted because it recited a feature already contained in claim 1.

Concerning the rejection of the claims under 35 U.S.C. 112, second paragraph, the Examiner will note that claim 1 has been amended to provide an antecedent basis for the limitations referred to by the Examiner.

Reconsideration and withdrawal of the rejection of the claims under 35 U.S.C. 102(e) as being anticipated by Hong, are also respectfully requested.

Applicants respectfully submit that the reference relied on by the Examiner does not disclose or suggest the miniaturized electrodynamic sounds transducer as it is claimed in the present application.

Specifically, aside from elements and features which are not recited in the claims of the application, the reference does not show a configuration of the housing and the magnet system which would be similar to the configuration of the sound transducer according to the present application. This is because the reference to Hong does not show a housing as it is provided in accordance with the present invention as claimed. The transducer according to the reference is composed of a magnet system with a lower pole part 30 which simultaneously serves as a bottom part, and of an annular support part 20. If the annular support part 20 is to be considered a housing, as the Examiner has stated in the Office Action, it is clear that this housing does not have a bottom and, therefore, the reference cannot disclose or suggest the most important feature of the present invention, i.e., the configuration of the upper and lower pole parts with a thickness which corresponds to at least 1.5 times the average thickness of the bottom of the housing.

In addition, applicants respectfully point out that there is technologically a huge difference between a transducer with a diameter of 80mm and a transducer with a diameter of 20mm because this linear reduction of the diameter by $1/4$ results in a reduction of the surfaces by $1/16$ and a reduction of the volumes and, thus, the masses, by $1/64$. This has extremely important consequences especially with respect to the mechanical stability, so that the formation of a bottom part (or bottom portion or bottom area) from the housing material is essential. It must also be taken into consideration that when the transducer has the claimed wall thicknesses (0.2mm in the case of the housing), a positively locking engagement between two parts, such as the tongue and groove connection disclosed by Hong, is entirely impossible.

With respect to the dependent claims, applicants respectfully submit that these claims are also not anticipated or suggested by the reference because these claims depend from claim 1 which, as discussed above, is believed to be patentably distinct over the reference.

With respect to claim 7, applicants submit that here once again the housing of Hong does not have a bottom and, therefore, it is not possible to compare the thickness of the sidewall of

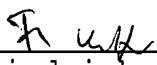
the magnet pot with the thickness of this bottom which is also not present. The same is true for claims 8 and 9 which just define different thickness ratios.

Therefore, in view of the foregoing, it is submitted that this application is now in condition for allowance and such allowance is respectfully solicited.

Any additional fees or charges required at this time in connection with the application may be charged to Patent and Trademark Office Deposit Account No. 11-1835.

Respectfully submitted,

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450, on November 17, 2005.

By: 

Friedrich Kueffner

Date: November 17, 2005